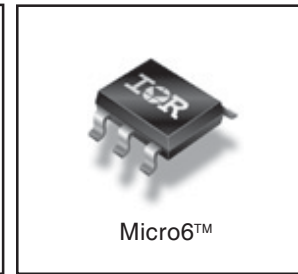
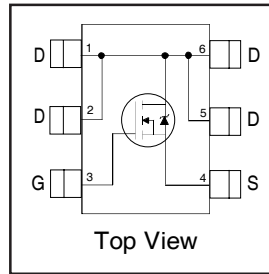


HEXFET® Power MOSFET

| | | |
|---|-------------|-----------|
| V_{DS} | 30 | V |
| $R_{DS(on) \max}$ (@ $V_{GS} = 10V$) | 0.10 | Ω |
| $R_{DS(on) \max}$ (@ $V_{GS} = 4.5V$) | 0.20 | |
| Q_g (typical) | 6.4 | nC |
| I_D (@ $T_A = 25^\circ C$) | 3.2 | A |



Features

| |
|---|
| Industry-standard pinout Micro-6 Package |
| Compatible with Existing Surface Mount Techniques |
| RoHS Compliant, Halogen-Free |
| MSL1, Industrial qualification |



Benefits

| |
|----------------------------|
| Multi-Vendor Compatibility |
| Easier Manufacturing |
| Environmentally Friendlier |
| Increased Reliability |

| Base Part Number | Package Type | Standard Pack | | Orderable Part Number |
|------------------|--------------|---------------|----------|-----------------------|
| | | Form | Quantity | |
| IRLMS1503TRPbF-1 | Micro6™ | Tape and Reel | 3000 | IRLMS1503TRPbF-1 |

Absolute Maximum Ratings

| | Parameter | Max. | Units |
|--------------------------|--|--------------|-------|
| $I_D @ T_A = 25^\circ C$ | Continuous Drain Current, $V_{GS} @ 10V$ | 3.2 | A |
| $I_D @ T_A = 70^\circ C$ | Continuous Drain Current, $V_{GS} @ 10V$ | 2.6 | |
| I_{DM} | Pulsed Drain Current ① | 18 | |
| $P_D @ T_A = 25^\circ C$ | Power Dissipation | 1.7 | W |
| | Linear Derating Factor | 13 | mW/°C |
| V_{GS} | Gate-to-Source Voltage | ± 20 | V |
| dv/dt | Peak Diode Recovery dv/dt ② | 5.0 | V/ns |
| T_J, T_{STG} | Junction and Storage Temperature Range | -55 to + 150 | °C |

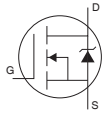
Thermal Resistance Ratings

| | Parameter | Min. | Typ. | Max | Units |
|-----------------|-------------------------------|------|------|-----|-------|
| $R_{\theta JA}$ | Maximum Junction-to-Ambient ④ | — | — | 75 | °C/W |

Electrical Characteristics @ T_J = 25°C (unless otherwise specified)

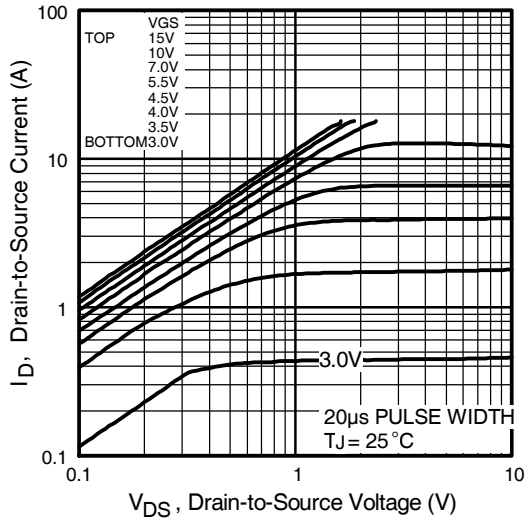
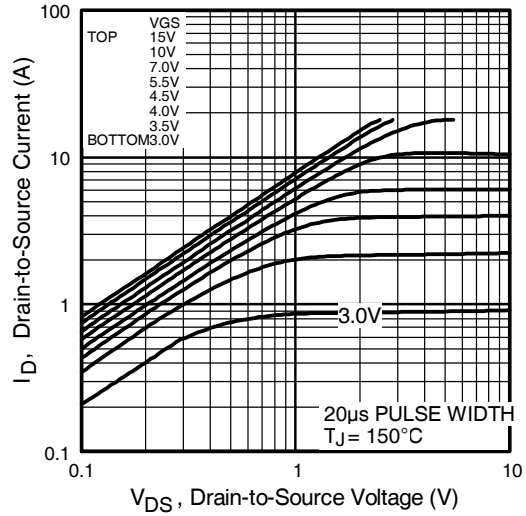
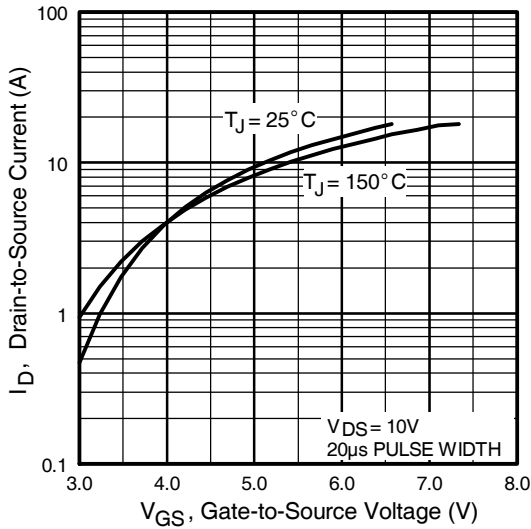
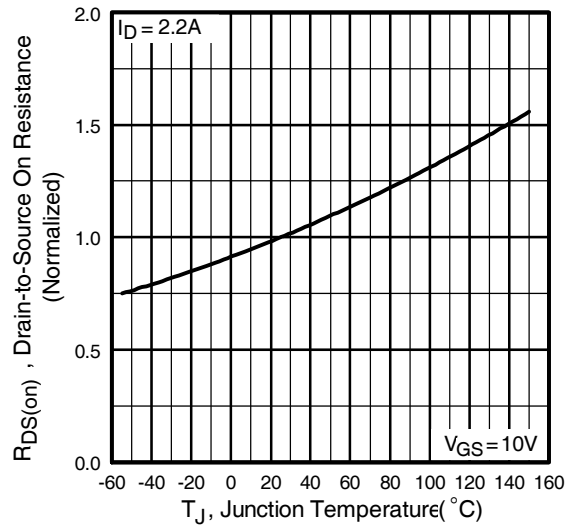
| | Parameter | Min. | Typ. | Max. | Units | Conditions |
|--------------------------------------|--------------------------------------|------|-------|---------------|-------|--|
| V _{(BR)DSS} | Drain-to-Source Breakdown Voltage | 30 | — | — | V | V _{GS} = 0V, I _D = 250μA |
| ΔV _{(BR)DSS/ΔT_J} | Breakdown Voltage Temp. Coefficient | — | 0.037 | — | V/°C | Reference to 25°C, I _D = 1mA |
| R _{DS(on)} | Static Drain-to-Source On-Resistance | — | — | 0.100 0.20 | Ω | V _{GS} = 10V, I _D = 2.2A ③ V _{GS} = 4.5V, I _D = 1.1A ③ |
| V _{GS(th)} | Gate Threshold Voltage | 1.0 | — | — | V | V _{DS} = V _{GS} , I _D = 250μA |
| g _{fs} | Forward Transconductance | 1.1 | — | — | S | V _{DS} = 10V, I _D = 1.1A |
| I _{DSS} | Drain-to-Source Leakage Current | — | — | 1.0 25 | μA | V _{DS} = 24V, V _{GS} = 0V V _{DS} = 24V, V _{GS} = 0V, T _J = 125°C |
| I _{GSS} | Gate-to-Source Forward Leakage | — | — | -100 | nA | V _{GS} = -20V |
| | Gate-to-Source Reverse Leakage | — | — | 100 | | V _{GS} = 20V |
| Q _g | Total Gate Charge | — | 6.4 | 9.6 | nC | I _D = 2.2A |
| Q _{gs} | Gate-to-Source Charge | — | 1.1 | 1.7 | | V _{DS} = 24V |
| Q _{gd} | Gate-to-Drain ("Miller") Charge | — | 1.9 | 2.8 | | V _{GS} = 10V, See Fig. 6 and 9 ③ |
| t _{d(on)} | Turn-On Delay Time | — | 4.6 | — | | V _{DD} = 15V |
| t _r | Rise Time | — | 4.4 | — | ns | I _D = 2.2A |
| t _{d(off)} | Turn-Off Delay Time | — | 10 | — | | R _G = 6.0Ω |
| t _f | Fall Time | — | 2.0 | — | | R _D = 6.7Ω, See Fig. 10 ③ |
| C _{iss} | Input Capacitance | — | 210 | — | pF | V _{GS} = 0V |
| C _{oss} | Output Capacitance | — | 90 | — | | V _{DS} = 25V |
| C _{rss} | Reverse Transfer Capacitance | — | 32 | — | | f = 1.0MHz, See Fig. 5 |

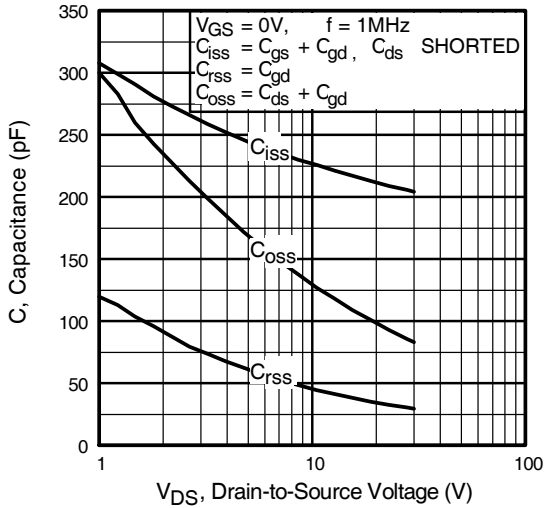
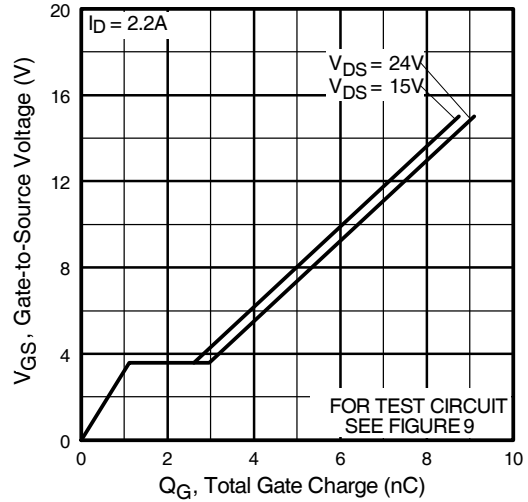
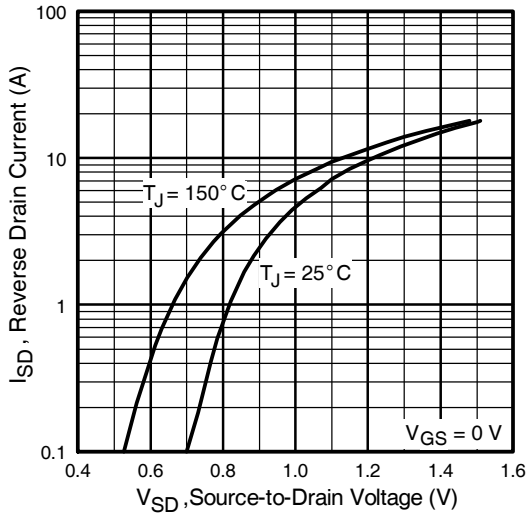
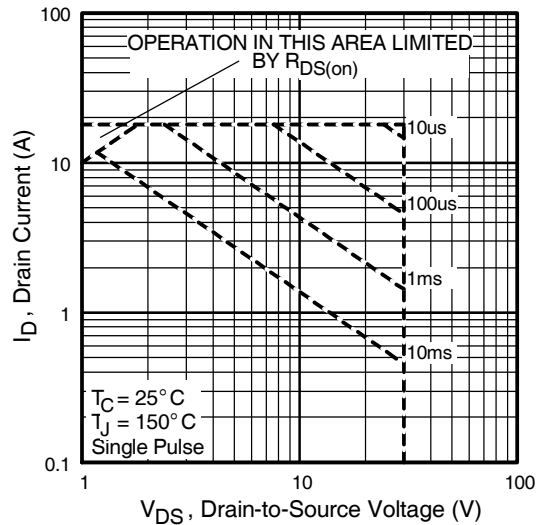
Source-Drain Ratings and Characteristics

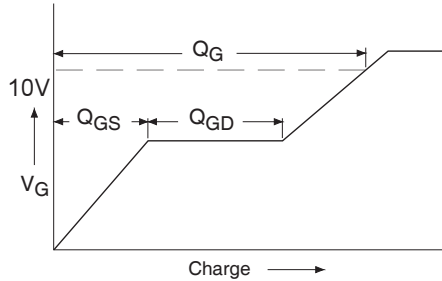
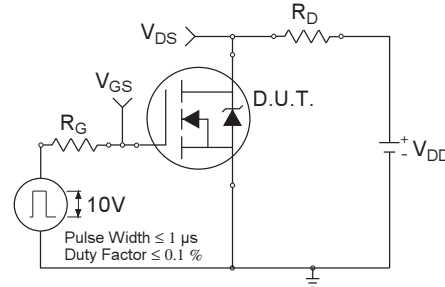
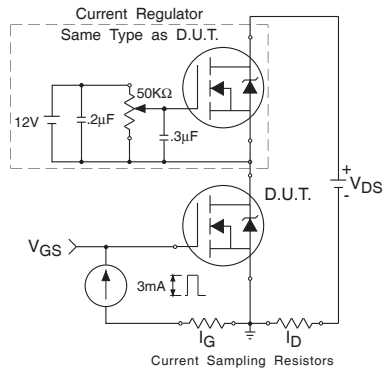
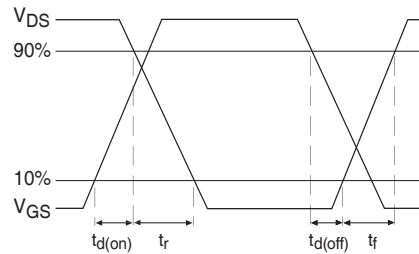
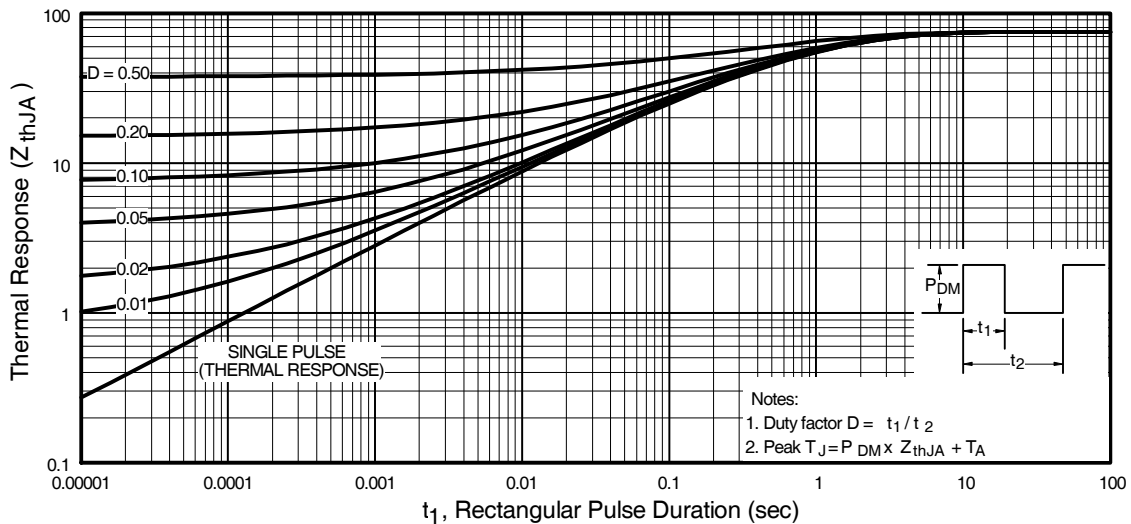
| | Parameter | Min. | Typ. | Max. | Units | Conditions |
|-----------------|--|------|------|------|-------|--|
| I _S | Continuous Source Current (Body Diode) | — | — | 1.7 | A | MOSFET symbol showing the integral reverse p-n junction diode.  |
| I _{SM} | Pulsed Source Current (Body Diode) ① | — | — | 18 | | |
| V _{SD} | Diode Forward Voltage | — | — | 1.2 | V | T _J = 25°C, I _S = 2.2A, V _{GS} = 0V ③ |
| t _{rr} | Reverse Recovery Time | — | 36 | 54 | ns | T _J = 25°C, I _F = 2.2A |
| Q _{rr} | Reverse Recovery Charge | — | 39 | 58 | nC | di/dt = 100A/μs ③ |

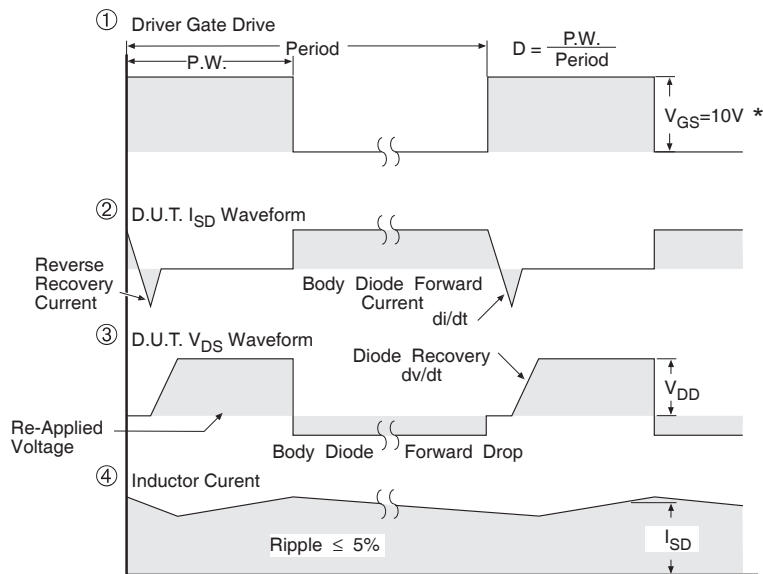
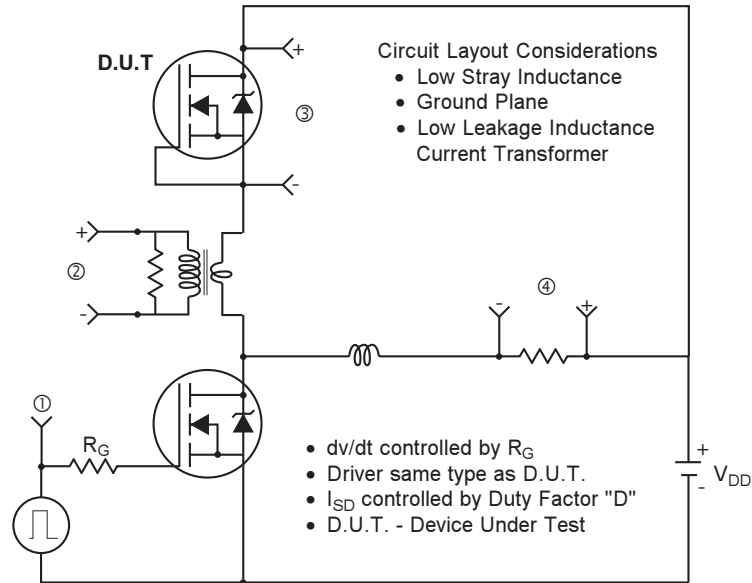
Notes:

- ① Repetitive rating; pulse width limited by max. junction temperature. (See fig. 11)
- ② I_{SD} ≤ 2.2A, di/dt ≤ 150A/μs, V_{DD} ≤ V_{(BR)DSS}, T_J ≤ 150°C
- ③ Pulse width ≤ 300μs; duty cycle ≤ 2%.
- ④ Surface mounted on FR-4 board, t ≤ 5sec.


Fig 1. Typical Output Characteristics

Fig 2. Typical Output Characteristics

Fig 3. Typical Transfer Characteristics

Fig 4. Normalized On-Resistance Vs. Temperature


Fig 5. Typical Capacitance Vs. Drain-to-Source Voltage

Fig 6. Typical Gate Charge Vs. Gate-to-Source Voltage

Fig 7. Typical Source-Drain Diode Forward Voltage

Fig 8. Maximum Safe Operating Area


Fig 9a. Basic Gate Charge Waveform

Fig 10a. Switching Time Test Circuit

Fig 9b. Gate Charge Test Circuit

Fig 10b. Switching Time Waveforms

Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

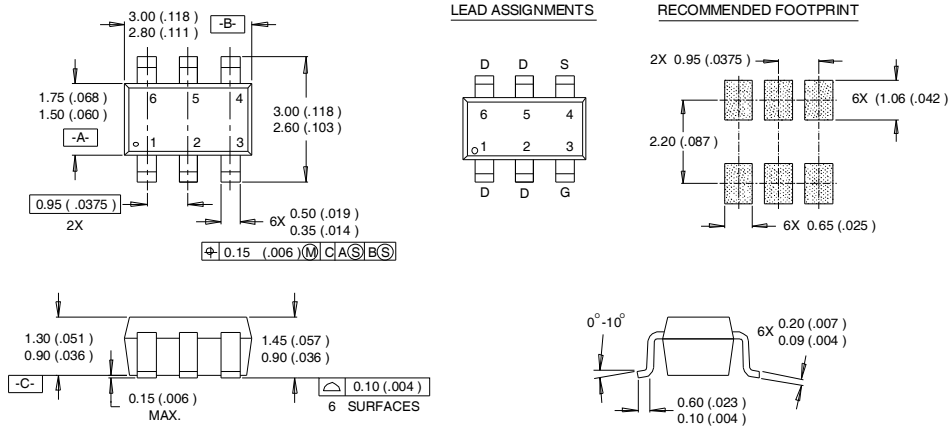
Peak Diode Recovery dv/dt Test Circuit


* $V_{GS} = 5V$ for Logic Level Devices

Fig 13. For N-channel HEXFET[®] power MOSFET s

Micro6 (SOT23 6L) Package Outline

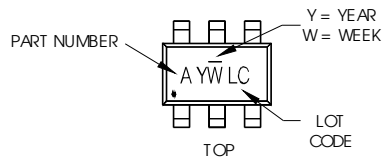
Dimensions are shown in millimeters (inches)



- NOTES :
1. DIMENSIONING & TOLERANCING PER ANSI Y14.5M-1982.
 2. CONTROLLING DIMENSION : MILLIMETER.
 3. DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).

Micro6 (SOT23 6L) Part Marking Information

W = (1-26) IF PRECEDED BY LAST DIGIT OF CALENDAR YEAR



PART NUMBER CODE REFERENCE:

- A = IRLMS1902
- B = IRLMS1503
- C = IRLMS6702
- D = IRLMS5703
- E = IRLMS6802
- F = IRLMS4502
- G = IRLMS2002
- H = IRLMS6803

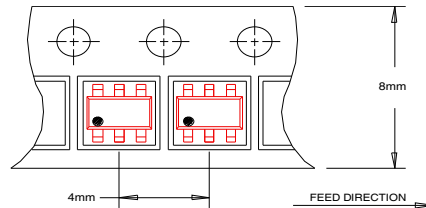
Note: A line above the work week (as shown here) indicates Lead-Free.

| YEAR | Y | WORK WEEK | W |
|------|---|-----------|---|
| 2001 | 1 | 01 | A |
| 2002 | 2 | 02 | B |
| 2003 | 3 | 03 | C |
| 2004 | 4 | 04 | D |
| 2005 | 5 | | |
| 2006 | 6 | | |
| 2007 | 7 | | |
| 2008 | 8 | | |
| 2009 | 9 | | |
| 2010 | 0 | 24 | X |
| | | 25 | Y |
| | | 26 | Z |

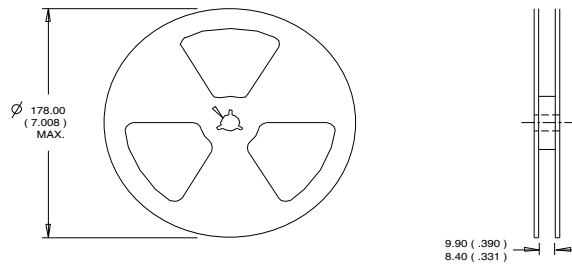
W = (27-52) IF PRECEDED BY A LETTER

| YEAR | Y | WORK WEEK | W |
|------|---|-----------|---|
| 2001 | A | 27 | A |
| 2002 | B | 28 | B |
| 2003 | C | 29 | C |
| 2004 | D | 30 | D |
| 2005 | E | | |
| 2006 | F | | |
| 2007 | G | | |
| 2008 | H | | |
| 2009 | J | | |
| 2010 | K | 50 | X |
| | | 51 | Y |
| | | 52 | Z |

Note: For the most current drawing please refer to IR website at <http://www.irf.com/package/>

Micro6 Tape & Reel Information (Dimensions are shown in millimeters (inches))


NOTES:
1. OUTLINE CONFORMS TO EIA-481 & EIA-541.



NOTES:
1. CONTROLLING DIMENSION : MILLIMETER.
2. OUTLINE CONFORMS TO EIA-481 & EIA-541.

Note: For the most current drawing please refer to IR website at <http://www.irf.com/package/>

Qualification information[†]

| | | |
|----------------------------|--|---|
| Qualification level | Industrial (per JEDEC JESD47F ^{††} guidelines) | |
| Moisture Sensitivity Level | Micro6™ | MSL1 (per JEDEC J-STD-020D ^{††}) |
| RoHS compliant | Yes | |

[†] Qualification standards can be found at International Rectifier's web site: <http://www.irf.com/product-info/reliability>

^{††} Applicable version of JEDEC standard at the time of product release

International
 Rectifier

IR WORLD HEADQUARTERS: 101 N. Sepulveda Blvd., El Segundo, California 90245, USA

To contact International Rectifier, please visit <http://www.irf.com/whoto-call/>

单击下面可查看定价，库存，交付和生命周期等信息

[>>Infineon Technologies\(英飞凌\)](#)